

255. (New) The integrated circuit package of claim 252 wherein the die comprises one or more memory circuits.

256. (New) The integrated circuit package of claim 252, wherein the die comprises one or more logic circuits.

257. (New) The integrated circuit package of claim 252, wherein the die comprises one or more application specific integrated circuits.

258. (New) The integrated circuit package of claim 252, wherein the material comprises a poly epoxide formed from one epoxide.

259. (New) The integrated circuit package of claim 252, wherein the material comprises a poly epoxide formed from two or more epoxides.

260. (New) The integrated circuit package of claim 252, wherein the material comprises a polyacrylate.

261. (New) An integrated circuit package comprising:  
a substrate;  
a die; and  
a material having a coefficient of thermal expansion  $\alpha_2$  of between about 151 (one-hundred and fifty-one) and about 400 (four-hundred)] ppm/ $^{\circ}$ C attaching the die to the substrate.

262. (New) The integrated circuit package of claim 261, wherein the material comprises a polyolefin.

263. (New) The integrated circuit package of claim 261, wherein the material comprises a polyimide.

264. (New) The integrated circuit package of claim 261, wherein the material comprises a mixture of at least two of a poly epoxide, polyacrylate, polyimide, and polyolefin.

265. (New) The integrated circuit package of claim 261, wherein the material comprises a copolymer of at least two of a poly epoxide, a polyacrylate, polyimide, and polyolefin.

266. (New) The integrated circuit package of claim 261, wherein the material comprises a mixture of a poly epoxide and a polyimide.

267. (New) The integrated circuit package of claim 261, wherein the material comprises a copolymer of a poly epoxide and a polyimide.

268. (New) The integrated circuit package of claim 261, wherein the material has a Shore A hardness of greater than about 70.

269. (New) The integrated circuit package of claim 261, wherein the material has a Shore D hardness of greater than about 20.

**REMARKS**

Applicant has reviewed and considered the office action mailed on June 5, 2002 and the references cited therewith.

Claims 127-135 are cancelled, and claims 252-269 are added; as a result, claims 1-52, 108-126, 136-154 and 252-269 are now pending in the application.

Support for new claim 252 and 261 is found, for example, at page 8, lines 11-12. Support for new claims 253-260 and 262-269 is found, for example, at pages 13 and 15.